

Composition and Utilization of This Brochure

Matters related to protection from bodily injury and prevention of property damage when handling semiconductor devices are stipulated first in Section 2 Safety Precautions.

General precautions and usage considerations to be observed at each stage of device handling are stipulated in Sections 3 and 4. Section 3 stipulates general precautions to be taken when handling any semiconductor product; Section 4 stipulates specific precautions for each product group individually. If the same item is described in Sections 3 and 4, the description in Section 4 takes precedence.

The precautions described here are not just those related to design, but cover all stages of handling, from reception of an incoming shipment to device inspection and mounting. Designers of systems incorporating semiconductor devices are requested to ensure that the contents of this brochure are fully understood by all relevant personnel, so that devices can be used safely and in the correct manner. It is also requested that relevant precautions be stipulated in the user's manuals for systems comprising semiconductor devices.

Note that software development tools are described in user's manuals which are available separately from Toshiba.